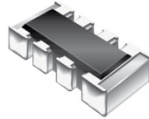


MATERIAL DECLARATION SHEET



Material Number	CAY10A-x4AS			
Product Line	Chip Resistor Array			
Compliance Date	2019/9/9			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.002381687	Aluminum oxide	1344-28-1	96%	83.91%	87.41%
				Magnesium oxide	14808-82-7	1%	0.87%	
				Silicon dioxide	1309-48-4	3%	2.62%	
2	Conductor Layer	Conductor Layer	0.000076837	Silver	7440-22-4	95%	2.68%	2.82%
				Palladium	7440-05-3	1%	0.03%	
				Glass	65997-17-3	4%	0.11%	
3	Resistive Element	Resistive Element	0.000064031	Ruthenium (IV) oxide	12036-10-1	25%	0.59%	2.35%
				Silver	7440-22-4	40%	0.94%	
				Palladium	7440-5-3	15%	0.35%	
				Lead-containing glass	7439-92-1	20%	0.47%	
4	Over-Coating	Epoxy	0.000030517	Epoxy	25068-38-6	52%	0.58%	1.12%
				Talc	14807-96-6	8%	0.09%	
				Silicon dioxide	60676-86-0	40%	0.45%	
5	Marking	Ink	0.000003270	Epoxy	25085-99-8	55%	0.07%	0.12%
				Barium sulfate	7727-43-7	15%	0.02%	
				Titanium dioxide	13463-67-7	30%	0.04%	
6	End Terminal	Metal	0.000002452	Silver	7440-22-4	80%	0.07%	0.09%
				Resins	25085-99-8	20%	0.02%	
7	Ni Plating	Nickel	0.000087736	Nickel	7440-02-0	100%	3.22%	3.22%
8	Sn Plating	Tin	0.0000782	Tin	7440-31-5	100%	2.87%	2.87%

MATERIAL DECLARATION SHEET

Total weight	0.00272473
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This Document was updated on: 2019/9/9

Important remarks: Resistive Element contains the Lead (Pb) which can be referred to RoHS Exemption 7(c)-I